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(71) Applicant *(for all designated States except US)*: **CABOT MICROELECTRONICS CORPORATION** [US/US]; 870 North Commons Drive, Aurora, IL 60504 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **GRUMBINE, Steven** [US/US]; 870 N. Commons Drive, Aurora, IL 60504 (US). **NAGUIB, Nevin** [US/US]; 870 N. Commons Drive, Aurora, IL 60504 (US).

(74) Agents: **WESEMAN, Steven** et al.; Legal Department, Cabot Microelectronics Corporation, 870 N. Commons Dr., Aurora, IL 60504 (US).

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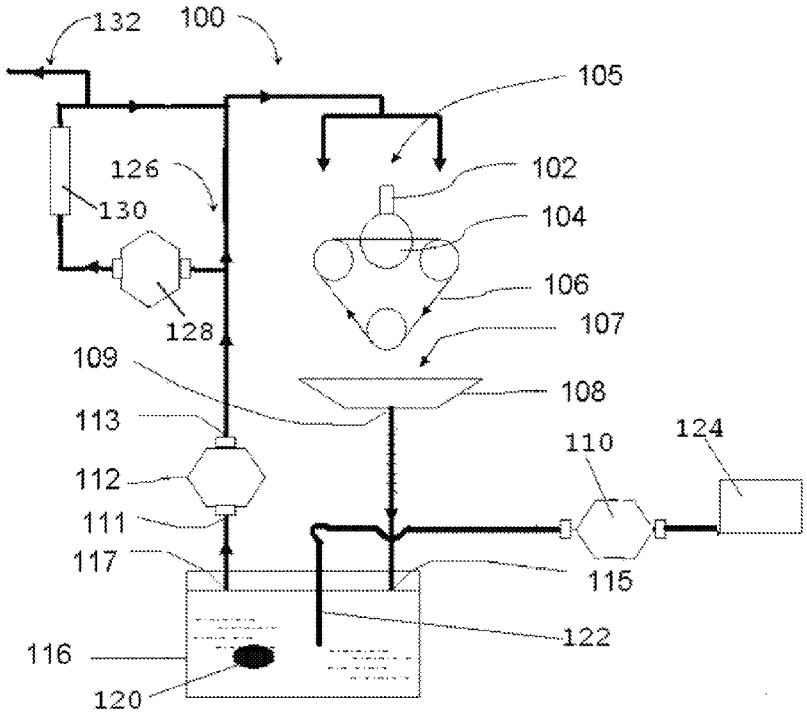
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(54) Title: WIRESAW CUTTING METHOD

(57) Abstract: The present invention provides a wiresaw cutting method comprising cutting a workpiece with a wiresaw while applying an aqueous cutting fluid to the wiresaw from a recirculating reservoir of cuttting fluid, monitoring at least one of a chemical property, a physical property, or both, and adjusting the chemical composition of the cutting fluid while cutting the workpiece to maintain the property being monitored. The present invention additionally provides an apparatus to perform the inventive method.

FIG. 1



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